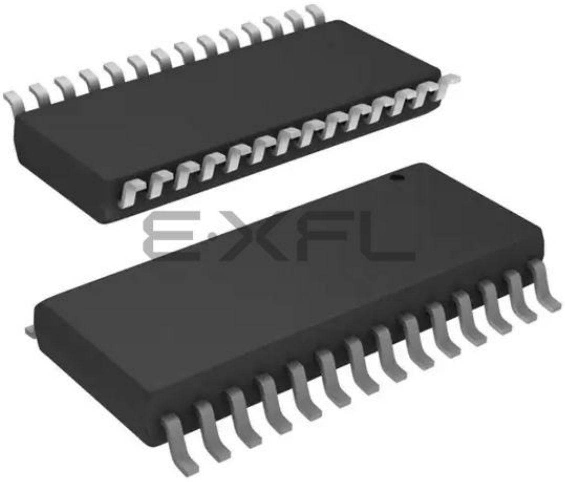
Microchip Technology - DSPIC33EP256MC202-E/SO Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mc202-e-so

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at **docerrors@microchip.com**. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000000A is version A of document DS30000000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; **http://www.microchip.com**
- Your local Microchip sales office (see last page)

When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at **www.microchip.com** to receive the most current information on all of our products.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the “Communication Channel Select” (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

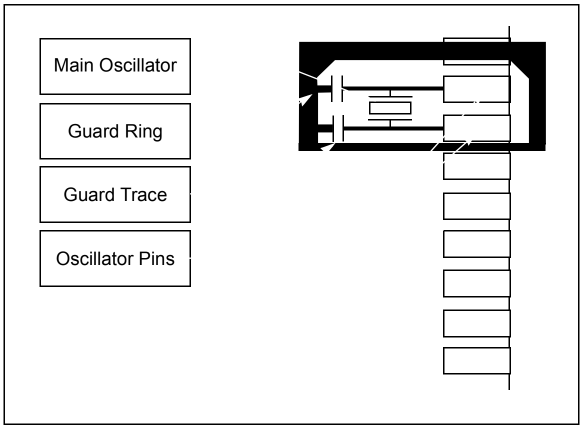
- *“Using MPLAB® ICD 3”* (poster) DS51765
- *“MPLAB® ICD 3 Design Advisory”* DS51764
- *“MPLAB® REAL ICE™ In-Circuit Emulator User’s Guide”* DS51616
- *“Using MPLAB® REAL ICE™ In-Circuit Emulator”* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 “Oscillator Configuration”** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



REGISTER 3-2: CORCON: CORE CONTROL REGISTER (CONTINUED)

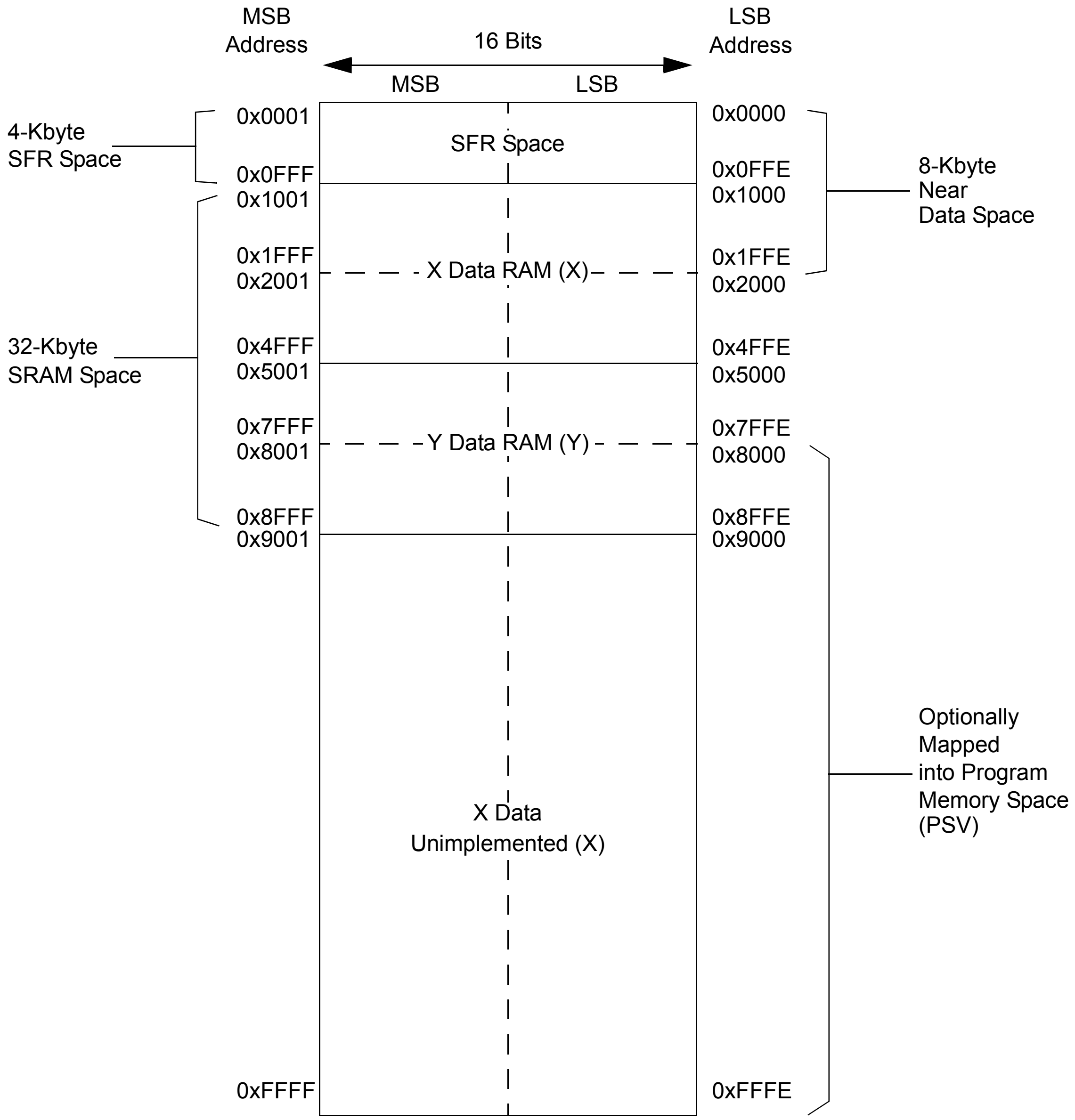
bit 2	**SFA:** Stack Frame Active Status bit `1` = Stack frame is active; W14 and W15 address 0x0000 to 0xFFFF, regardless of DSRPAG and DSWPAG values `0` = Stack frame is not active; W14 and W15 address of EDS or Base Data Space
bit 1	**RND:** Rounding Mode Select bit(1) `1` = Biased (conventional) rounding is enabled `0` = Unbiased (convergent) rounding is enabled
bit 0	**IF:** Integer or Fractional Multiplier Mode Select bit(1) `1` = Integer mode is enabled for DSP multiply `0` = Fractional mode is enabled for DSP multiply

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

2: This bit is always read as ‘`0`’.

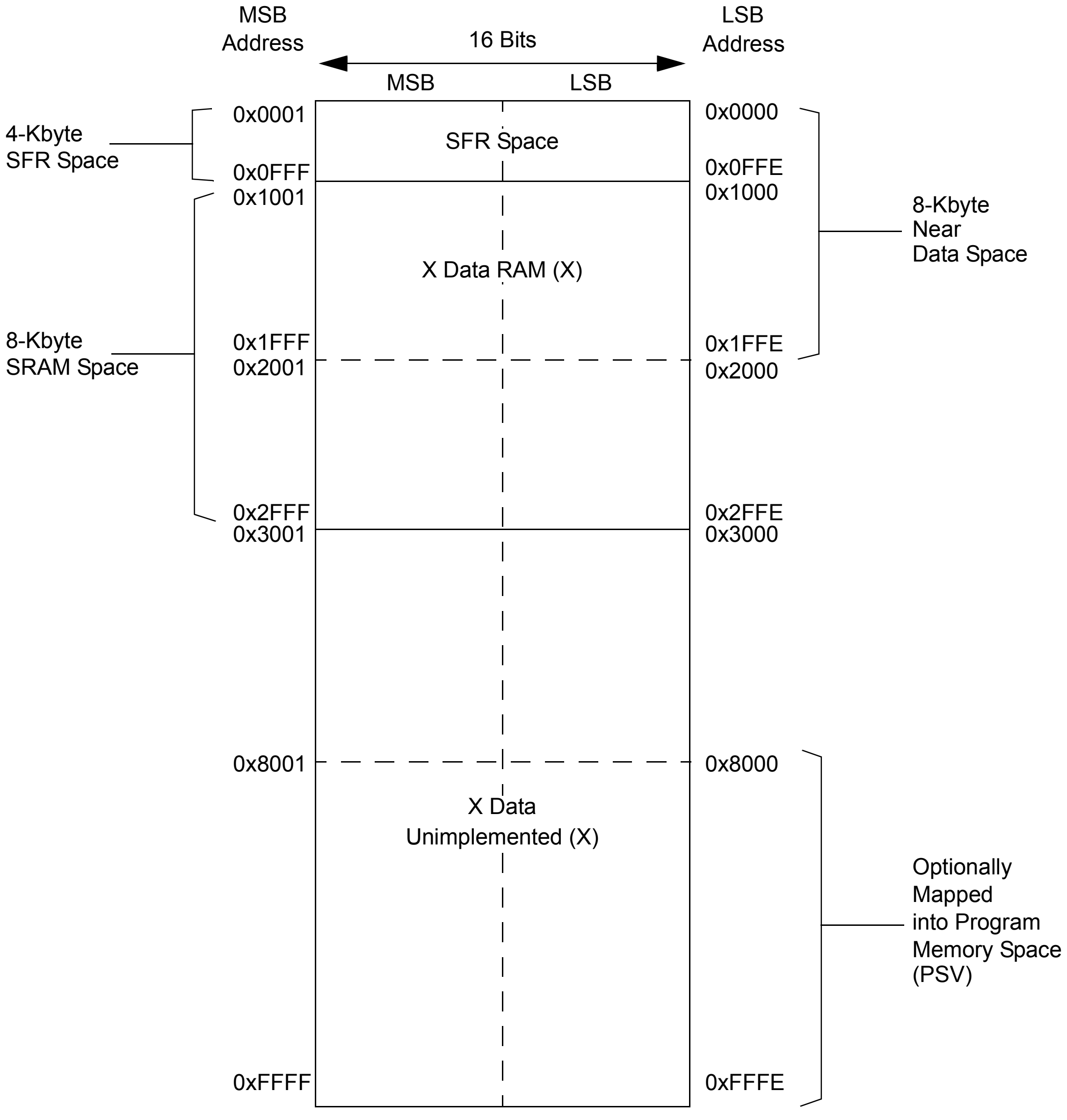
3: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

FIGURE 4-10: DATA MEMORY MAP FOR dsPIC33EP256MC20X/50X AND dsPIC33EP256GP50X DEVICES



Note: Memory areas are not shown to scale.

FIGURE 4-13: DATA MEMORY MAP FOR PIC24EP64GP/MC20X/50X DEVICES



Note: Memory areas are not shown to scale.

REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
ROI	DOZE2(1)	DOZE1(1)	DOZE0(1)	DOZEN(2,3)	FRCDIV2	FRCDIV1	FRCDIV0
bit 15							bit 8

R/W-0	R/W-1	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PLLPOST1	PLLPOST0	—	PLLPRE4	PLLPRE3	PLLPRE2	PLLPRE1	PLLPRE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ROI:** Recover on Interrupt bit

1 = Interrupts will clear the DOZEN bit
0 = Interrupts have no effect on the DOZEN bit

bit 14-12 **DOZE<2:0>:** Processor Clock Reduction Select bits(1)

111 = FCY divided by 128
110 = FCY divided by 64
101 = FCY divided by 32
100 = FCY divided by 16
011 = FCY divided by 8 (default)
010 = FCY divided by 4
001 = FCY divided by 2
000 = FCY divided by 1

bit 11 **DOZEN:** Doze Mode Enable bit(2,3)

1 = DOZE<2:0> field specifies the ratio between the peripheral clocks and the processor clocks
0 = Processor clock and peripheral clock ratio is forced to 1:1

bit 10-8 **FRCDIV<2:0>:** Internal Fast RC Oscillator Postscaler bits

111 = FRC divided by 256
110 = FRC divided by 64
101 = FRC divided by 32
100 = FRC divided by 16
011 = FRC divided by 8
010 = FRC divided by 4
001 = FRC divided by 2
000 = FRC divided by 1 (default)

bit 7-6 **PLLPOST<1:0>:** PLL VCO Output Divider Select bits (also denoted as ‘N2’, PLL postscaler)

11 = Output divided by 8
10 = Reserved
01 = Output divided by 4 (default)
00 = Output divided by 2

bit 5 **Unimplemented:** Read as ‘0’

Note 1: The DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.

2: This bit is cleared when the ROI bit is set and an interrupt occurs.

3: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

REGISTER 11-9: RPINR15: PERIPHERAL PIN SELECT INPUT REGISTER 15 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	HOME1R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	INDX1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘`0`’

bit 14-8 **HOME1R<6:0>:** Assign QEI1 HOME1 (HOME1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`1111001` = Input tied to RPI121
.
.
.
`0000001` = Input tied to CMP1
`0000000` = Input tied to VSS

bit 7 **Unimplemented:** Read as ‘`0`’

bit 6-0 **IND1XR<6:0>:** Assign QEI1 INDEX1 (INDX1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`1111001` = Input tied to RPI121
.
.
.
`0000001` = Input tied to CMP1
`0000000` = Input tied to VSS

REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH[1]	BCL[1]	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**PHR:** PWMxH Rising Edge Trigger Enable bit 1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores rising edge of PWMxH
bit 14	**PHF:** PWMxH Falling Edge Trigger Enable bit 1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores falling edge of PWMxH
bit 13	**PLR:** PWMxL Rising Edge Trigger Enable bit 1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores rising edge of PWMxL
bit 12	**PLF:** PWMxL Falling Edge Trigger Enable bit 1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter 0 = Leading-Edge Blanking ignores falling edge of PWMxL
bit 11	**FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit 1 = Leading-Edge Blanking is applied to selected Fault input 0 = Leading-Edge Blanking is not applied to selected Fault input
bit 10	**CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit 1 = Leading-Edge Blanking is applied to selected current-limit input 0 = Leading-Edge Blanking is not applied to selected current-limit input
bit 9-6	**Unimplemented:** Read as ‘0’
bit 5	**BCH:** Blanking in Selected Blanking Signal High Enable bit[1] 1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high 0 = No blanking when selected blanking signal is high
bit 4	**BCL:** Blanking in Selected Blanking Signal Low Enable bit[1] 1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low 0 = No blanking when selected blanking signal is low
bit 3	**BPHH:** Blanking in PWMxH High Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high 0 = No blanking when PWMxH output is high
bit 2	**BPHL:** Blanking in PWMxH Low Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low 0 = No blanking when PWMxH output is low
bit 1	**BPLH:** Blanking in PWMxL High Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high 0 = No blanking when PWMxL output is high
bit 0	**BPLL:** Blanking in PWMxL Low Enable bit 1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low 0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

REGISTER 21-2: CxCTRL2: ECANx CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	DNCNT4	DNCNT3	DNCNT2	DNCNT1	DNCNT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘`0`’

bit 4-0 **DNCNT<4:0>:** DeviceNet™ Filter Bit Number bits

`10010-11111` = Invalid selection
`10001` = Compares up to Data Byte 3, bit 6 with EID<17>
•
•
•
`00001` = Compares up to Data Byte 1, bit 7 with EID<0>
`00000` = Does not compare data bytes

26.3 Programmable CRC Registers

REGISTER 26-1: CRCCON1: CRC CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R-0	R-0	R-0	R-0	R-0
CRCEN	—	CSIDL	VWORD4	VWORD3	VWORD2	VWORD1	VWORD0
bit 15							bit 8

R-0	R-1	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
CRCFUL	CRCMPT	CRCISEL	CRCGO	LENDIAN	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CRCEN:** CRC Enable bit

`1` = CRC module is enabled
`0` = CRC module is disabled; all state machines, pointers and CRCWDAT/CRCDAT are reset, other SFRs are not reset

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **CSIDL:** CRC Stop in Idle Mode bit

`1` = Discontinues module operation when device enters Idle mode
`0` = Continues module operation in Idle mode

bit 12-8 **VWORD<4:0>:** Pointer Value bits

Indicates the number of valid words in the FIFO. Has a maximum value of 8 when PLEN<4:0> > 7 or 16 when PLEN<4:0> ≤ 7.

bit 7 **CRCFUL**: CRC FIFO Full bit

`1` = FIFO is full
`0` = FIFO is not full

bit 6 **CRCMPT:** CRC FIFO Empty Bit

`1` = FIFO is empty
`0` = FIFO is not empty

bit 5 **CRCISEL:** CRC Interrupt Selection bit

`1` = Interrupt on FIFO is empty; final word of data is still shifting through CRC
`0` = Interrupt on shift is complete and CRCWDAT results are ready

bit 4 **CRCGO:** Start CRC bit

`1` = Starts CRC serial shifter
`0` = CRC serial shifter is turned off

bit 3 **LENDIAN:** Data Word Little-Endian Configuration bit

`1` = Data word is shifted into the CRC starting with the LSb (little endian)
`0` = Data word is shifted into the CRC starting with the MSb (big endian)

bit 2-0 **Unimplemented:** Read as ‘`0`’

REGISTER 26-3: CRCXORH: CRC XOR POLYNOMIAL HIGH REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0	**X<31:16>:** XOR of Polynomial Term X^n Enable bits

REGISTER 26-4: CRCXORL: CRC XOR POLYNOMIAL LOW REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
X<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
X<7:1>							—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-1	**X<15:1>:** XOR of Polynomial Term X^n Enable bits
bit 0	**Unimplemented:** Read as ‘`0`’

TABLE 27-2: CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Description
WDTPRE	Watchdog Timer Prescaler bit 1 = 1:128 0 = 1:32
WDTPOST<3:0>	Watchdog Timer Postscaler bits 1111 = 1:32,768 1110 = 1:16,384 • • • 0001 = 1:2 0000 = 1:1
WDTWIN<1:0>	Watchdog Window Select bits 11 = WDT window is 25% of WDT period 10 = WDT window is 37.5% of WDT period 01 = WDT window is 50% of WDT period 00 = WDT window is 75% of WDT period
ALTI2C1	Alternate I2C1 pin 1 = I2C1 is mapped to the SDA1/SCL1 pins 0 = I2C1 is mapped to the ASDA1/ASCL1 pins
ALTI2C2	Alternate I2C2 pin 1 = I2C2 is mapped to the SDA2/SCL2 pins 0 = I2C2 is mapped to the ASDA2/ASCL2 pins
JTAGEN(2)	JTAG Enable bit 1 = JTAG is enabled 0 = JTAG is disabled
ICS<1:0>	ICD Communication Channel Select bits 11 = Communicate on PGEC1 and PGED1 10 = Communicate on PGEC2 and PGED2 01 = Communicate on PGEC3 and PGED3 00 = Reserved, do not use

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: When JTAGEN = 1, an internal pull-up resistor is enabled on the TMS pin. Erased devices default to JTAGEN = 1. Applications requiring I/O pins in a high-impedance state (tri-state) in Reset should use pins other than TMS for this purpose.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles[2]	Status Flags Affected
52	`MUL`	`MUL.SS Wb,Ws,Wnd`	{Wnd + 1, Wnd} = signed(Wb) * signed(Ws)	1	1	None
		`MUL.SS Wb,Ws,Acc`[1]	Accumulator = signed(Wb) * signed(Ws)	1	1	None
		`MUL.SU Wb,Ws,Wnd`	{Wnd + 1, Wnd} = signed(Wb) * unsigned(Ws)	1	1	None
		`MUL.SU Wb,Ws,Acc`[1]	Accumulator = signed(Wb) * unsigned(Ws)	1	1	None
		`MUL.SU Wb,#lit5,Acc`[1]	Accumulator = signed(Wb) * unsigned(lit5)	1	1	None
		`MUL.US Wb,Ws,Wnd`	{Wnd + 1, Wnd} = unsigned(Wb) * signed(Ws)	1	1	None
		`MUL.US Wb,Ws,Acc`[1]	Accumulator = unsigned(Wb) * signed(Ws)	1	1	None
		`MUL.UU Wb,Ws,Wnd`	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(Ws)	1	1	None
		`MUL.UU Wb,#lit5,Acc`[1]	Accumulator = unsigned(Wb) * unsigned(lit5)	1	1	None
		`MUL.UU Wb,Ws,Acc`[1]	Accumulator = unsigned(Wb) * unsigned(Ws)	1	1	None
		`MULW.SS Wb,Ws,Wnd`	Wnd = signed(Wb) * signed(Ws)	1	1	None
		`MULW.SU Wb,Ws,Wnd`	Wnd = signed(Wb) * unsigned(Ws)	1	1	None
		`MULW.US Wb,Ws,Wnd`	Wnd = unsigned(Wb) * signed(Ws)	1	1	None
		`MULW.UU Wb,Ws,Wnd`	Wnd = unsigned(Wb) * unsigned(Ws)	1	1	None
		`MUL.SU Wb,#lit5,Wnd`	{Wnd + 1, Wnd} = signed(Wb) * unsigned(lit5)	1	1	None
		`MUL.SU Wb,#lit5,Wnd`	Wnd = signed(Wb) * unsigned(lit5)	1	1	None
		`MUL.UU Wb,#lit5,Wnd`	{Wnd + 1, Wnd} = unsigned(Wb) * unsigned(lit5)	1	1	None
		`MUL.UU Wb,#lit5,Wnd`	Wnd = unsigned(Wb) * unsigned(lit5)	1	1	None
		`MUL f`	W3:W2 = f * WREG	1	1	None

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage**	3.0	—	3.6	V	
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.03	—	—	V/ms	0V-1V in 100 ms

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

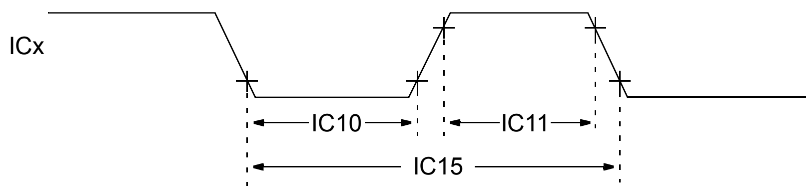
TABLE 30-5: FILTER CAPACITOR (CEFC) SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated):
Operating temperature -40°C ≤ TA ≤ +85°C for Industrial
-40°C ≤ TA ≤ +125°C for Extended

Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
	CEFC	External Filter Capacitor Value[1]	4.7	10	—	μF	Capacitor must have a low series resistance (< 1 Ohm)

Note 1: Typical VCAP voltage = 1.8 volts when VDD ≥ VDDMIN.

FIGURE 30-6: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS



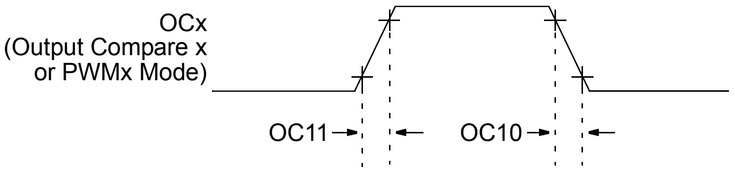
Note: Refer to Figure 30-1 for load conditions.

TABLE 30-26: INPUT CAPTURE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	T_{CCL}	ICx Input Low Time	Greater of 12.5 + 25 or (0.5 T_{CY}/N) + 25	—	ns	Must also meet Parameter IC15	N = prescale value (1, 4, 16)
IC11	T_{CCH}	ICx Input High Time	Greater of 12.5 + 25 or (0.5 T_{CY}/N) + 25	—	ns	Must also meet Parameter IC15	
IC15	T_{CCP}	ICx Input Period	Greater of 25 + 50 or (1 T_{CY}/N) + 50	—	ns		

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-7: OUTPUT COMPARE x MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-27: OUTPUT COMPARE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-8: OCx/PWMx MODULE TIMING CHARACTERISTICS

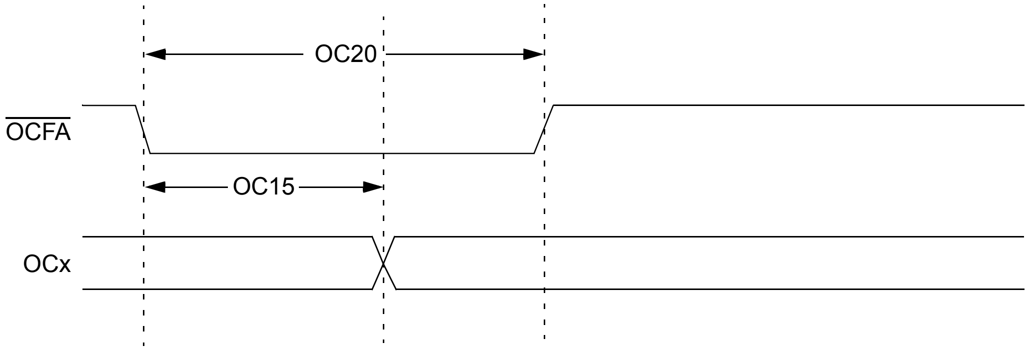


TABLE 30-28: OCx/PWMx MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWMx I/O Change	—	—	TCY + 20	ns	
OC20	TFLT	Fault Input Pulse Width	TCY + 20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 30-48: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = `0`, CKP = `0`, SMP = `0`) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SS1}}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SS1}}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{\text{SS1}}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 91 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

FIGURE 32-5: TYPICAL I_{PD} CURRENT @ V_{DD} = 3.3V

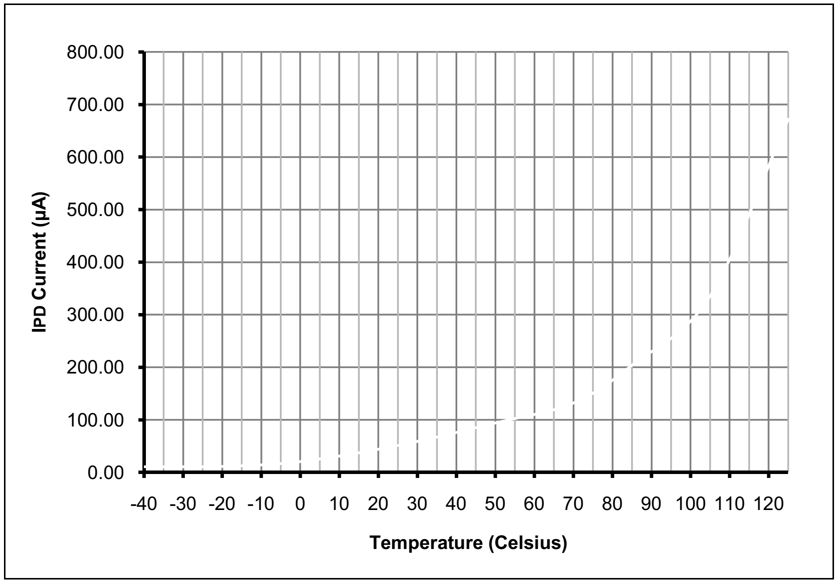


FIGURE 32-7: TYPICAL I_{DOZE} CURRENT @ V_{DD} = 3.3V

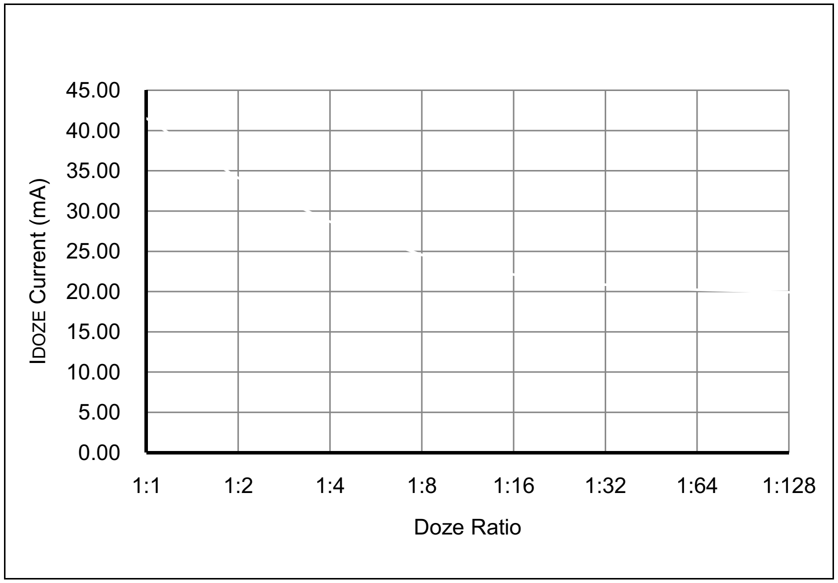


FIGURE 32-6: TYPICAL/MAXIMUM I_{DD} CURRENT @ V_{DD} = 3.3V

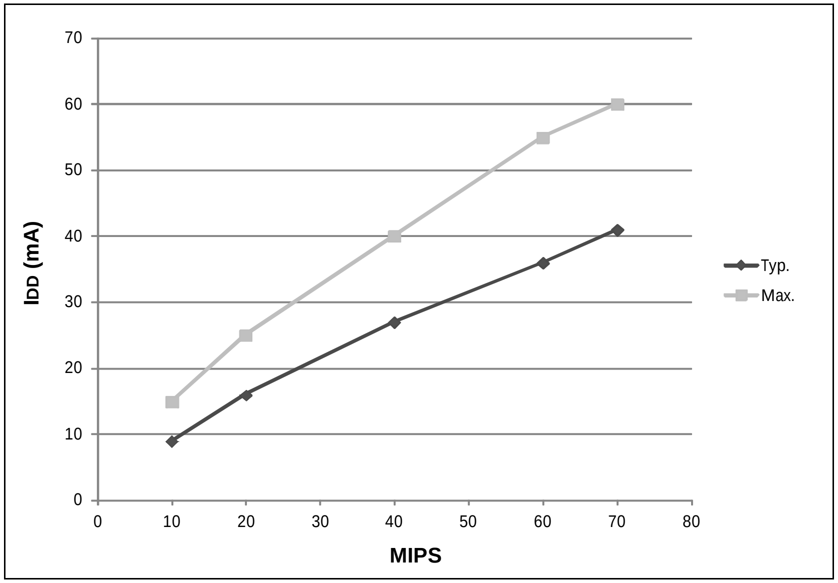
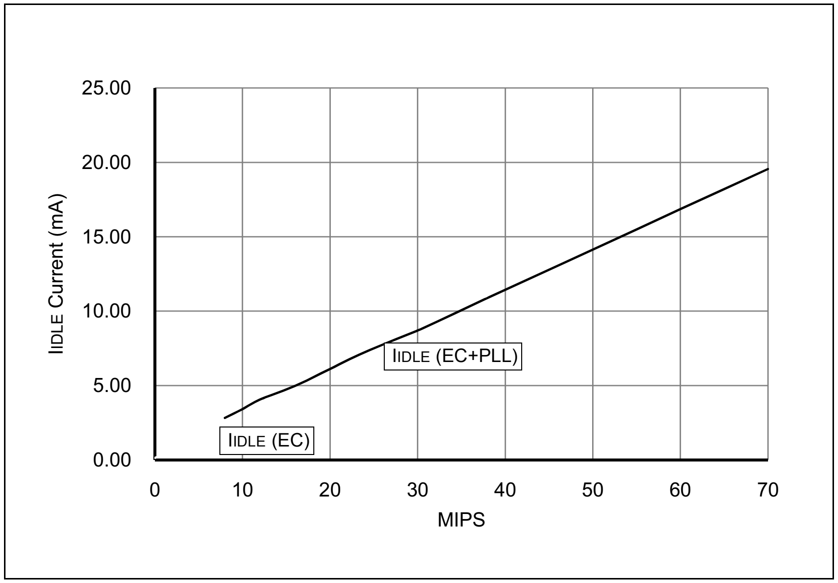
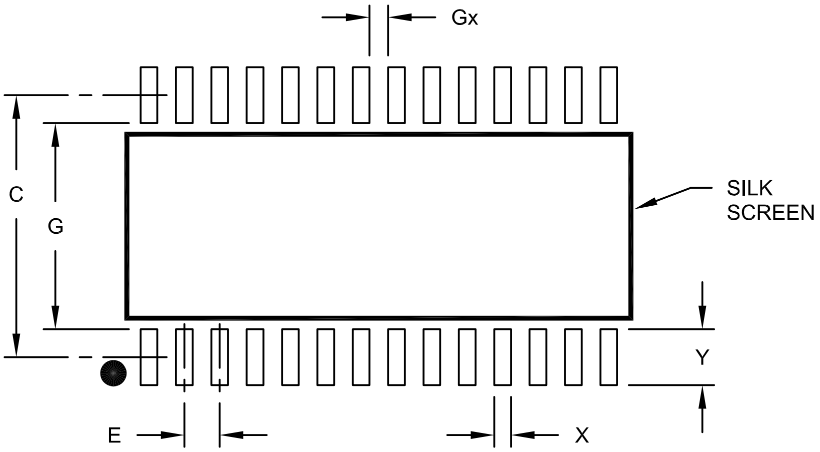


FIGURE 32-8: TYPICAL I_{IDLE} CURRENT @ V_{DD} = 3.3V



28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

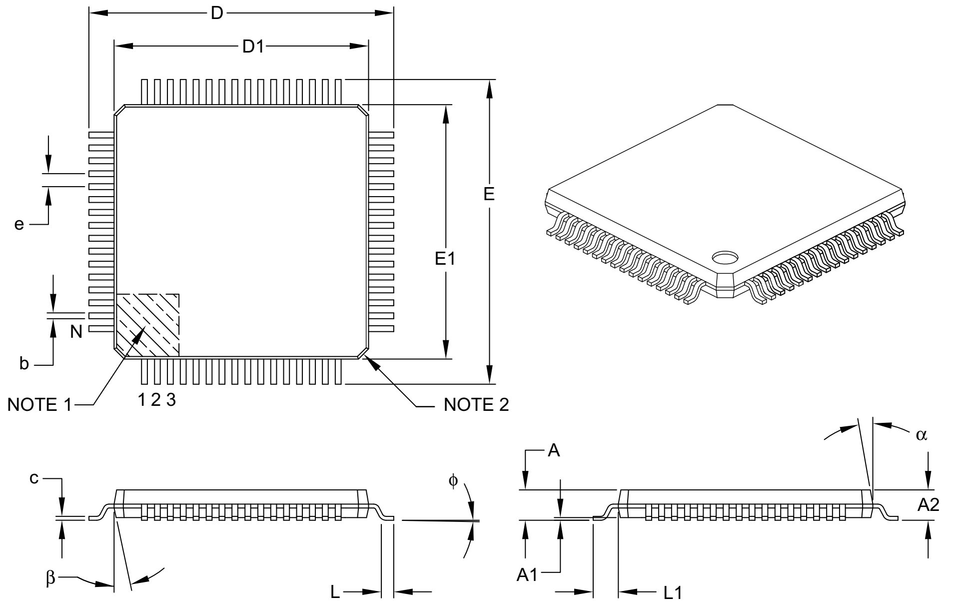
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.50 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
    BSC: Basic Dimension. Theoretically exact value shown without tolerances.
    REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B